

## Bill of Materials

TIDM-FRAM-WATERMETER

Item	Designator	Qty	Value	Part Description	Manufacturer	Manufacturer	Digikey	PCB Footprint	Note
	_			,		Part Number	Part Number	•	<u> </u>
	BT1	_	2460	Battery Holder, 1AA Cells, PC-mount	Keystone	2460	2460K-ND	BH1AA-PC	
2	C1		47uF	CAP, TA, 47uF, 6.3V, +/-10%, 0.8 ohm, SMD	AVX	TPSA476K006R0800	478-3079-1-ND	3216-18	
3	C2	1	10uF	CAP, TA, 10uF, 16V, +/-10%, 3 ohm, SMD	Vishay-Sprague	293D106X9016A2TE3	718-1123-1-ND	3216-18	
4	C3, C11, C51	3	10uF	CAP, CERM, 10uF, 6.3V, +/-20%, X5R, 0603	Kemet	C0603C106M9PACTU	399-5504-1-ND	0603	
5	C4, C10	2	1uF	CAP, CERM, 1uF, 16V, +/-10%, X5R, 0603	Kemet	C0603C105K4PACTU	399-5090-1-ND	0603	₩
6	C7, C8, C9, C41, C42, C43, C47, C49, C52	9	0.1uF	CAP, CERM, 0.1uF, 16V, +/-5%, X7R, 0603	Kemet	C0603C104J4RACTU	399-1097-1-ND	0603	
7	C46, C48	2	25pF	CAP, CERM, 25pF, 50V, +/-11%, COG/NPO, 0603	AVX	06035A2R2CAT2A	478-1155-1-ND	0603	
8	C5, C6, C50	3	1000pF	CAP, CERM, 1000pF, 100V, +/-5%, X7R, 0603	AVX	06031C102JAT2A	478-3698-1-ND	0603	
9	D1	1	Green	LED, Green, SMD	Lite-On	LTST-C170KRKT	160-1415-1-ND	LED_LTST-C170	
10	J1, J7, J8, J9	4	3x1	Header, TH, 100mil, 3x1, Gold plated, 230 mil above insulator	Samtec	TSW-103-07-G-S	SAM1029-03-ND	TSW-103-07-G-S	
11	J2, J3	2	4x1	Header, TH, 100mil, 4x1, Gold plated, 230 mil above insulator	Samtec	TSW-104-07-G-S	SAM1029-04-ND	TSW-104-07-G-S	
12	J4	1	3x2	Header, TH, 100mil, 3x2, Gold plated, 230 mil above insulator	Samtec	TSW-103-07-G-D	SAM1028-03-ND	TSW-103-07-G-D	
13	J6	1	5x1	Header, TH, 100mil, 5x1, Gold plated, 230 mil above insulator	Samtec	TSW-105-07-G-S	SAM1029-05-ND	TSW-105-07-G-S	
14	J11, J12	2	10x1	Header, TH, 100mil, 10x1, Gold plated, 230 mil above insulator	Samtec	TSW-110-07-G-S	SAM1029-10-ND	TSW-110-07-G-S	
15	LCD1	1	LCD	BTL002 4COM LCD	N/A	BTL002	N/A	LCD	
16	LS1	1	BEEPER	Loudspeaker	Soberton Inc	WST-1203UX	433-1047-ND	BEEPER	$\dagger$
17	Q2, Q3	2	PNP	Transistor, PNP, 40V, 0.2A, SOT-23	Diodes Inc.	MMBT3906-7-F	MMBT3906-FDICT-ND	SOT-23	
18	R3, R5	2	10k ohm	RES, 10k ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW060310K0JNEA	541-10KGCT-ND	0603	+
19	R4	1	120 ohm	RES, 120 ohm, 5%, 0.1W, 0603	Vishav-Dale	CRCW0603120RJNEA	541-120GCT-ND	0603	<b>†</b>
20	R21	1	47k ohm	RES, 47k ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW060347KOJNEA	541-47KGCT-ND	0603	$\vdash$
21	R2. R22	2	2.0k ohm	RES, 2.0k ohm, 5%, 0.1W, 0603	Vishay-Dale Vishay-Dale	CRCW060347KOJNEA	541-2.0KGCT-ND	0603	+-
22	R23	1	200 ohm	RES, 200 ohm, 5%, 0.1W, 0603	Vishay-Dale Vishay-Dale	CRCW0603200RJNEA	541-200GCT-ND	0603	╁
23	R25	1	50 ohm	RES, 50 ohm, 0.5%, 0.1W, 0603	Yageo America	RT0603DRE07150RL	RT0603DRE07150RL-ND	0603	$\leftarrow$
24	R101, R102	2	470k ohm	RES 470K OHM 1/10W 5% 0603 SMD	Yageo America	RC0603JR-07470KL	311-470KGRTR-ND	0603	╁
25	U1	1	TPS78233	IC, 150mA, Ultra-Low Quiescent Current, IQ 500nA LDO Linear Regulator	Texas Instruments	TPS78233DDCR	296-24059-1-ND	TSOT-23-5[DDC]	$\vdash$
26	U2	1	SN65HVD75	High Temperature 3.3 V RS-485 Transceiver	Texas Instruments	SN65HVD11SHKJ	296-28287-5-ND	D0008A N	$\vdash$
27	U4	1	MSP430FR4133	16-bit Ultra-Low-Power MCU	Texas Instruments	MSP430FR4133IPM	N/A	PM0064A M	$\vdash$
28	U10	1	DRV8837	LOW-VOLTAGE H-BRIDGE IC. DSG0008A	Texas Instruments	DRV8837DSG	296-34806-1-ND	DRV8837DSG	$\vdash$
29	Y1	1	32.768kHz	Crystal, 32.768kHz, 12.5pF, SMD	Abracon Corporation	AB26TRQ-32.768KHZ-T	535-12051-1-ND	XTAL MS3V-T1R	<b>†</b>
NC		-							
110	C12, C13, C14, C15, C16, C17, C18, C19,								
	C20, C21, C22, C23, C24, C25, C26, C27,	ĺ							1
	C28, C29, C30, C31, C32, C33, C34, C35,	ĺ							1
30	C36, C37, C38, C39	28	8.2pF	CAP, CERM, 8.2pF, 50V, +/-3%, COG/NPO, 0603	AVX	06035A8R2CAT2A	478-1162-1-ND	0603	
31	C45, R8, R10, R11, R14, R16, R17	7	NC	NC	NC	NC	NC	NC	
32	C40	1	100uF	CAP, TA, 100uF, 6.3V, +/-10%, 1.7 ohm, SMD	Vishay-Sprague	293D107X96R3B2TE3	718-1128-1-ND	3528-21	
33	C44	1	0.1uF	CAP, CERM, 0.1uF, 16V, +/-5%, X7R, 0603	Kemet	C0603C104J4RACTU	399-1097-1-ND	0603	
34	D3, D4	2	Diode	Diode, Schottky, 40V, 0.03A, SOD-323	Diodes Inc.	SDMK0340L-7-F	SDMK0340LDICT-ND	sod-323	
35	J5	1	2x1	Header, TH, 100mil, 2x1, Gold plated, 230 mil above insulator	Samtec	TSW-102-07-G-S	SAM1029-02-ND	TSW-102-07-G-S	
36	R9, R12	2	220 ohm	RES, 220 ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW0603220RJNEA	541-220GCT-ND	0603	
37	R15	1	100k ohm	RES, 100k ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW0603100KJNEA	541-100KGCT-ND	0603	
38	R18. R20	2	0 ohm	RES, 0 ohm, 5%, 0.1W, 0603	Vishav-Dale	CRCW06030000Z0EA	541-0.0GCT-ND	0603	†
39	R24	1	10.0k ohm	RES, 10.0k ohm, 0.1%, 0.1W, 0603	Susumu Co Ltd	RG1608P-103-B-T5	RG16P10.0KBCT-ND	0603	$\vdash$
40	U3	1	TSS721	METER-BUS Transceiver	Texas Instruments	TSS721A	296-27128-1-ND	D0016A N	$\vdash$
41	U5. U6	2	PS2501	High Isolation Voltage Single Transistor Type OptoCoupler	California Eastern Laboratories	PS2501L-1-A	PS2501L-1A-ND	PS2501L	$\vdash$
42	U7, U8, U12, U14, U15	5	TPD2E2U06	DUAL CHANNEL HIGH SPEED ESD PROTECTION DEVICE, DRL0005A	Texas Instruments	TPD2E2U06DRL	296-38361-1-ND	DRL0005A	+

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